

Adopt FRED chip  
 Low forward Voltage drop  
 Fast reverse recovery time  
 High frequency operation  
 High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance  
 Guard ring for enhanced ruggedness and long term reliability

Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

: TO-263

Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant

: Tin plated leads, solderable per J-STD-002 and JESD22-B102

: As marked

( $T_j=25$  Unless otherwise specified)

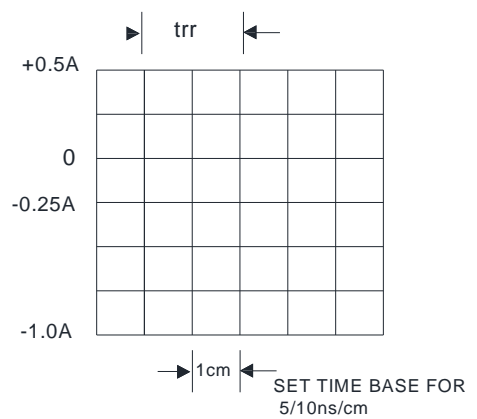

			-55 ~ +175
Junction Temperature	$T_j$		-55 ~ +175
Typical Junction capacitance @4V,1MHz	$C_j$	pF	50



Instantaneous forward voltage drop per diode	$V_{FM}$	V	$I_{FM}=5.0A @T_j=25$	-	0.90	1.0
			$I_{FM}=5.0A @T_j=150$		0.78	0.9
DC reverse current at rated DC blocking voltage per diode	$I_{RRM1}$	uA	$V_{RM}=V_{RRM}$ $T_j=25$	-	-	5.0
	$I_{RRM2}$		$V_{RM}=V_{RRM}$ $T_j=150$	-	25	50
			$I_F=0.5A I_{RM}=1A$ $I_{RR}=0.25A T_j=25$	-	25	35
Reverse Recovery Time	$T_{rr}$	ns				

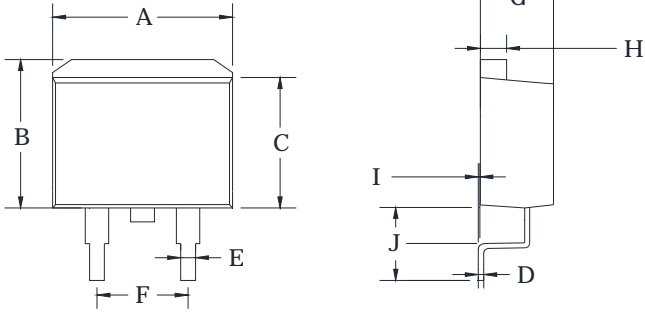


(Typical)





TO 263



Dim	Min	Max
A	9.5	11.5
B	9.7	10.5
C	8.4	9.0
D	0.28	0.64
E	0.68	0.94
F	4.55	5.6
G	4.04	5.10
H	1.14	1.4
I	0	0.2
J	4.9	6.05
K	1.79	2.79
L	7.3	7.9
M	6.2	6.8
N	7.6	8.2

Dimensions in millimeters



A	12.7
B	9.4
C	16.6
P	5.08
Q1	3.8
Q2	1.35

